

DOCKET NO: 312302US40PCT



IN THE UNITED STATES PATENT & TRADEMARK OFFICE

IN RE APPLICATION OF :  
HUI ZHONG, ET AL. : EXAMINER: TUAN T. DINH  
SERIAL NO: 10/049,270 :  
FILED: JUNE 27, 2002 : GROUP ART UNIT: 2841  
FOR: MULTILAYER PRINTED WIRING :  
BOARD, SOLDER RESIST  
COMPOSITION, METHOD FOR  
MANUFACTURING MULTILAYER  
PRINTED WIRING BOARD, AND  
SEMICONDUCTOR DEVICE

AMENDMENT

COMMISSIONER FOR PATENTS  
ALEXANDRIA, VIRGINIA 22313

SIR:

In response to the Office Action dated November 5, 2007, please amend the above-identified application as follows:

**Amendments to the Specification** begin on page 2 of this paper.

**Amendments to the Claims** are reflected in the listing of claims which begins on page 3 of this paper.

**Amendments to the Drawings** begin on page 6 of this paper and include an attached replacement sheet.

**Remarks/Arguments** begin on page 7 of this paper.